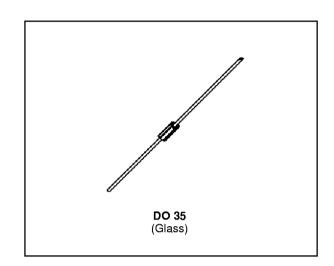
# SMALL SIGNAL SCHOTTKY DIODES



### **DESCRIPTION**

General purpose, metal to silicon diodes featuring very low turn-on voltage fast switching.

These devices have integrated protection against excessive voltage such as electrostatic discharges.

## **ABSOLUTE RATINGS** (limiting values)

Symbol	Parameter	Value	Unit		
V <sub>RRM</sub>	Repetitive Peak Reverse Voltage	30	V		
l <sub>F</sub>	Forward Continuous Current	200	mA		
I <sub>FRM</sub>	Repetitive Peak Fordware Current	500	mA		
I <sub>FSM</sub>	Surge non Repetitive Forward Current* t	4	Α		
P <sub>tot</sub>	Power Dissipation*	T₁= 65 °C	200	mW	
T <sub>stg</sub> T <sub>j</sub>	Storage and Junction Temperature Range		- 65 to +150 - 65 to +125	°C	
TL	Maximum Temperature for Soldering during 10s at 4mm from Case 230				

#### THERMAL RESISTANCE

Symbol	Test Conditions	Value	Unit
R <sub>th(j-a)</sub>	Junction-ambient*	300	°C/W

<sup>\*</sup> On infinite heatsink with 4mm lead length

November 1994

#### **ELECTRICAL CHARACTERISTICS**

## STATIC CHARACTERISTICS

Symbol		Test Condition s	Min.	Тур.	Max.	Unit	
$V_{BR}$	Tj = 25°C	$I_R = 100 \mu A$		30			V
V <sub>F</sub> *	T <sub>j</sub> = 25°C	$I_F = 200 \text{mA}$	All Types			1	V
	T <sub>j</sub> = 25°C	$I_F = 10mA$	BAT 42			0.4	
	T <sub>j</sub> = 25°C	I <sub>F</sub> = 50mA				0.65	
	T <sub>j</sub> = 25°C	I <sub>F</sub> = 2mA	BAT 43	0.26		0.33	
	T <sub>j</sub> = 25°C	I <sub>F</sub> = 15mA				0.45	
l <sub>R</sub> *	T <sub>j</sub> = 25°C		V <sub>R</sub> = 25V			0.5	μА
	T <sub>j</sub> = 100°C					100	

#### **DYNAMIC CHARACTERISTICS**

Symbol	Test Condition s	Min.	Тур.	Max.	Unit
С	$T_j = 25^{\circ}C$ $V_R = 1V$ $f = 1MHz$		7		pF
trr	$Tj = 25^{\circ}C$ $I_F = 10mA$ $I_R = 10mA$ $I_{rr} = 1mA$ $R_L = 100\Omega$			5	ns
h	$T_j = 25^{\circ}C$ $R_L = 15K\Omega$ $C_L = 300pF$ $f = 45MHz$ $V_i = 2V$	80	·		%

<sup>\*</sup> Pulse test:  $t_p \le 300 \mu s$   $\delta < 2\%$ .

Figure 1. Forward current versus forward voltage at different temperatures (typical values).

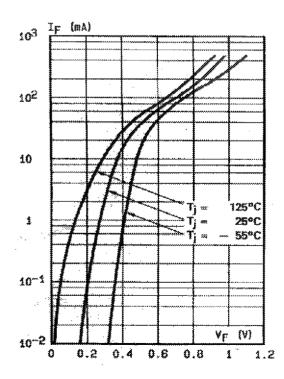


Figure 2. Forward current versus forward voltage (typical values).

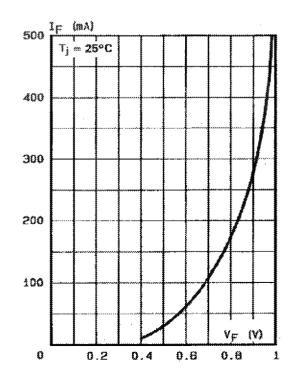


Figure 3. Reverse current versus junction temperature (typical values).

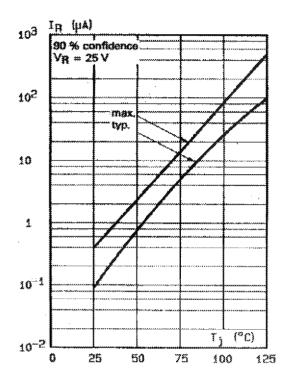


Figure 4. Reverse current versus continuous reverse voltage.

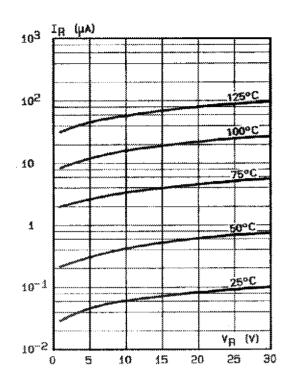
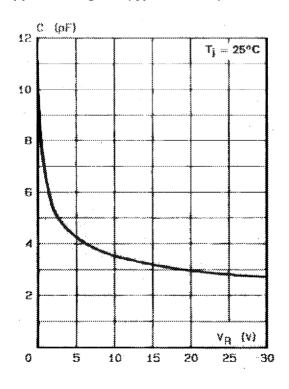
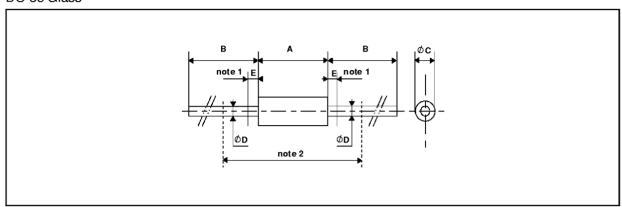


Figure 5. Capacitance C versus reverse applied voltage  $V_{\rm R}$  (typical values).



#### **PACKAGE MECHANICAL DATA**

#### DO 35 Glass



DIMENSIONS							
REF.	EF. Millimeters		Inches		NOTES		
	Min.	Max.	Min.	Max.			
Α	3.050	4.500	0.120	0.117			
В	12.7		0.500		1 - The lead diameter Ø D is not controlled over zone E		
ØC	1.530	2.000	0.060	0.079	2 - The minimum axial lengh within which the device may be placed		
ØD	0.458	0.558	0.018	0.022	with its leads bent at right angles is 0.59"(15 mm)		
Е		1.27		0.050			

Cooling method: by convection and conduction Marking: clear, ring at cathode end. Weight: 0.15g

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